

Title (en)

INTEGRATED CIRCUIT CHIP MADE SECURE AGAINST THE ACTION OF ELECTROMAGNETIC RADIATION

Title (de)

INTEGRIERTER SCHALTKREIS-CHIP, GESCHÜTZT GEGEN DIE BEHANDLUNG MIT ELEKTROMAGNETISCHER STRAHLUNG

Title (fr)

PUCE A CIRCUITS INTEGRES SECURISEE CONTRE L'ACTION DE RAYONNEMENTS ELECTROMAGNETIQUES

Publication

**EP 1127376 A1 20010829 (FR)**

Application

**EP 99947524 A 19991008**

Priority

- FR 9902428 W 19991008
- FR 9813029 A 19981016

Abstract (en)

[origin: FR2784768A1] An integrated circuit (5) may be protected from maloperation due to the incidence of infrared electromagnetic radiation by a doped layer, an irregular surface or a metallic screen. Where doping is used it comprises the addition of some 10<sup>19</sup> atoms of Phosphorus or Boron per cm<sup>3</sup> in a layer (14) located above the processor, memory units and contacts (8) of the integrated circuit

IPC 1-7

**H01L 23/552**; G06K 19/073

IPC 8 full level

**B42D 15/10** (2006.01); **G06K 19/073** (2006.01); **G06K 19/077** (2006.01); **H01L 21/822** (2006.01); **H01L 23/552** (2006.01); **H01L 27/04** (2006.01)

CPC (source: EP US)

**G06K 19/073** (2013.01 - EP US); **G06K 19/07372** (2013.01 - EP US); **H01L 23/552** (2013.01 - EP US); **H01L 24/48** (2013.01 - EP US); **H01L 2224/05599** (2013.01 - EP US); **H01L 2224/451** (2013.01 - EP US); **H01L 2224/48091** (2013.01 - EP US); **H01L 2224/48227** (2013.01 - EP US); **H01L 2224/48465** (2013.01 - EP US); **H01L 2224/85399** (2013.01 - EP US); **H01L 2924/00014** (2013.01 - EP US); **H01L 2924/01005** (2013.01 - EP US); **H01L 2924/01013** (2013.01 - EP US); **H01L 2924/01019** (2013.01 - EP US); **H01L 2924/01024** (2013.01 - EP US); **H01L 2924/01033** (2013.01 - EP US); **H01L 2924/01046** (2013.01 - EP US); **H01L 2924/01051** (2013.01 - EP US); **H01L 2924/0106** (2013.01 - EP US); **H01L 2924/01061** (2013.01 - EP US); **H01L 2924/01079** (2013.01 - EP US); **H01L 2924/01082** (2013.01 - EP US); **H01L 2924/01094** (2013.01 - EP US); **H01L 2924/13091** (2013.01 - EP US); **H01L 2924/14** (2013.01 - EP US); **H01L 2924/181** (2013.01 - EP US)

Citation (search report)

See references of WO 0024058A1

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